

## Description

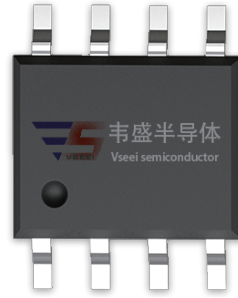
The VSM8P03 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V.

## General Features

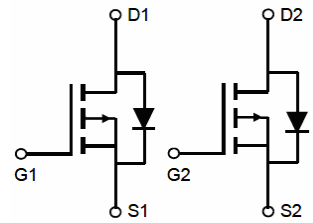
- $V_{DS} = -30V, I_D = -8A$   
 $R_{DS(ON)} < 35m\Omega @ V_{GS} = -4.5V$   
 $R_{DS(ON)} < 20m\Omega @ V_{GS} = -10V$
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

## Application

- Battery Switch
- Load switch
- Power management



SOP-8



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM8P03-S8	VSM8P03	SOP-8	Ø330mm	12mm	4000 units

## Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-8	A
Drain Current-Continuous( $T_C = 100^\circ\text{C}$ )	$I_D(100^\circ\text{C})$	-5.7	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	-32	A
Maximum Power Dissipation	$P_D$	3.1	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ\text{C}$

## Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	40	$^\circ\text{C/W}$
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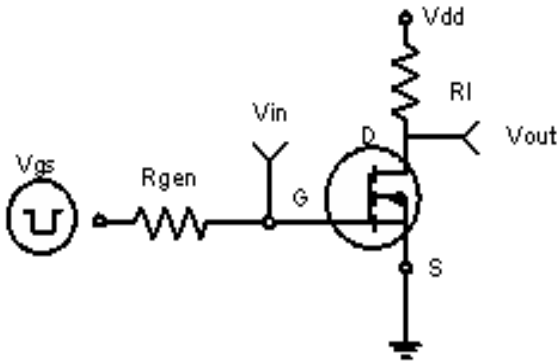
**Electrical Characteristics ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-1	-1.5	-3	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-8A	-	16	20	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A	-	21	35	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V,I <sub>D</sub> =-8A	10	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-15V,V <sub>GS</sub> =0V, F=1.0MHz	-	1600	-	PF
Output Capacitance	C <sub>oss</sub>		-	350	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	300	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V, ID=-8A, V <sub>GS</sub> =-10V,R <sub>GEN</sub> =6Ω	-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	15	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	110	-	nS
Turn-Off Fall Time	t <sub>f</sub>			70	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-15V,I <sub>D</sub> =-8A V <sub>GS</sub> =-10V	-	30	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	5.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	8	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-8A	-	-	-1.2	V

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

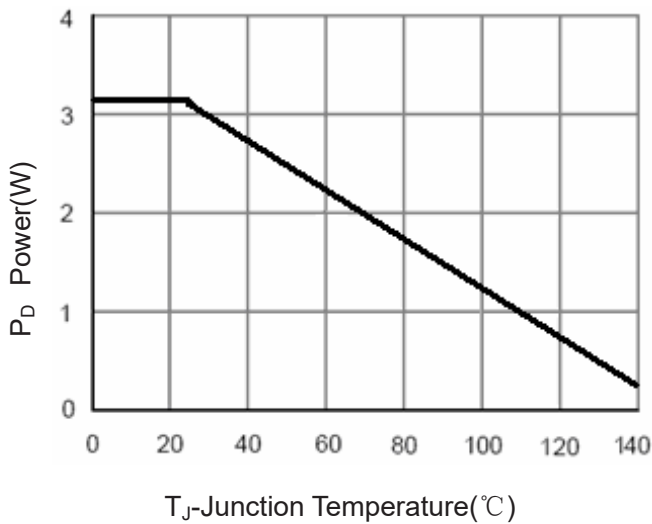
## Typical Electrical and Thermal Characteristics



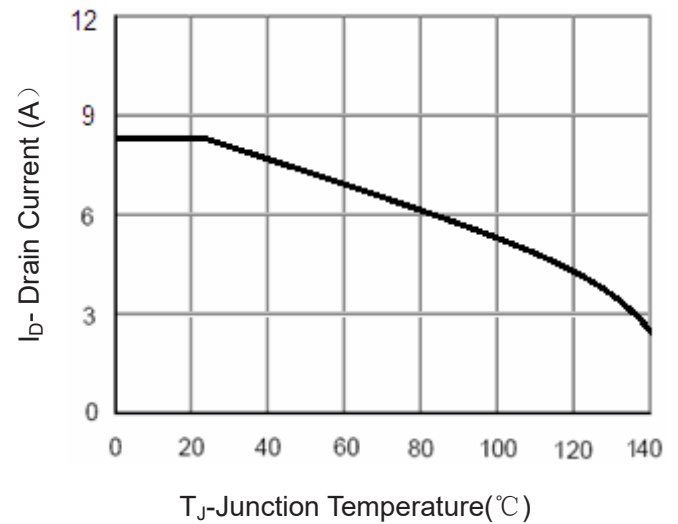
**Figure 1: Switching Test Circuit**



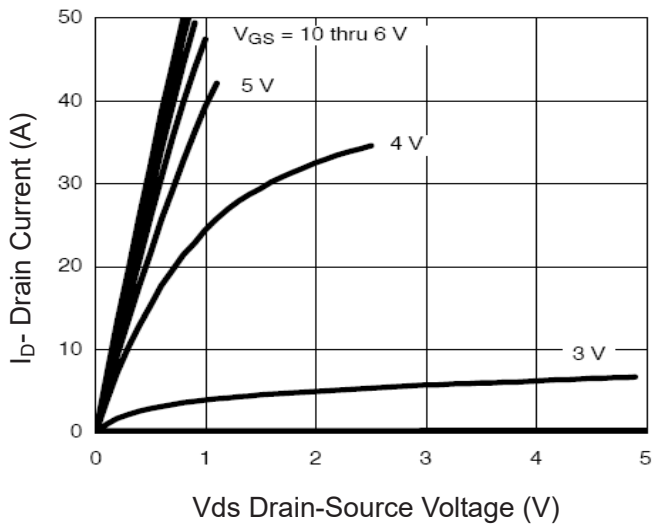
**Figure 2: Switching Waveforms**



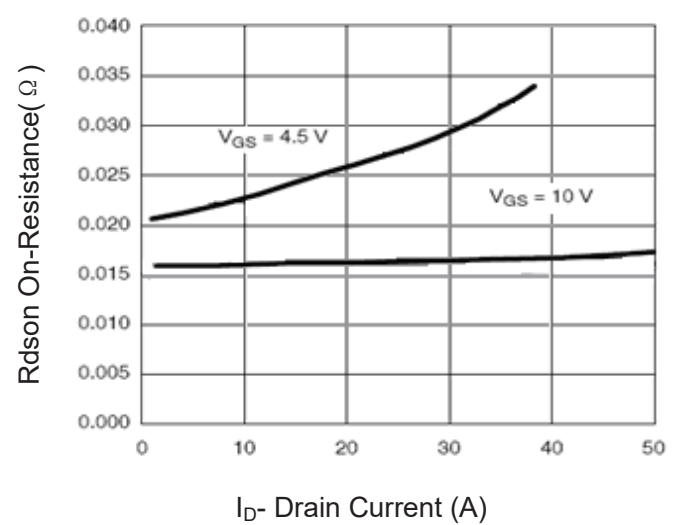
**Figure 3 Power Dissipation**



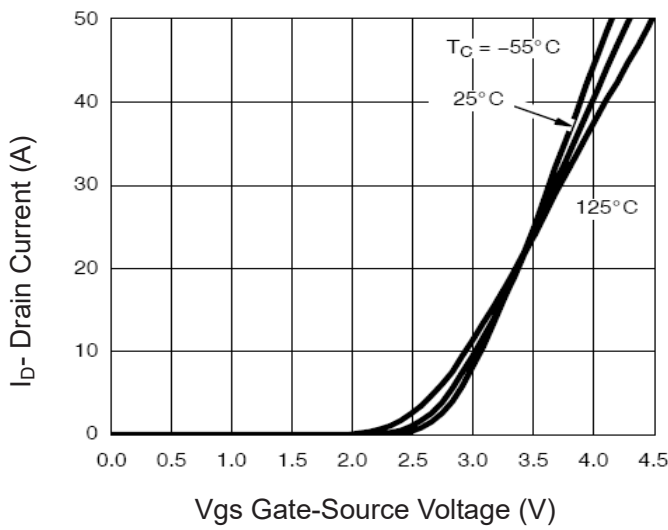
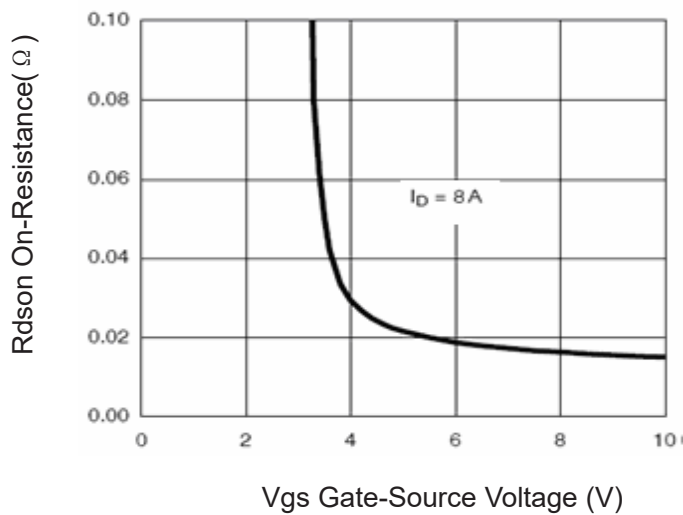
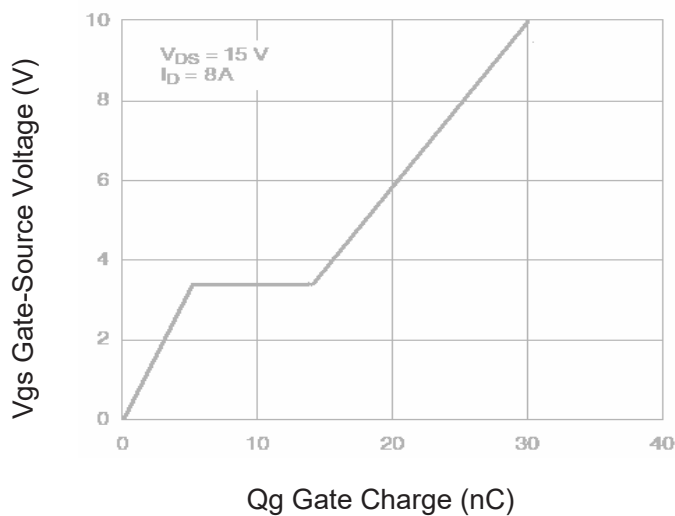
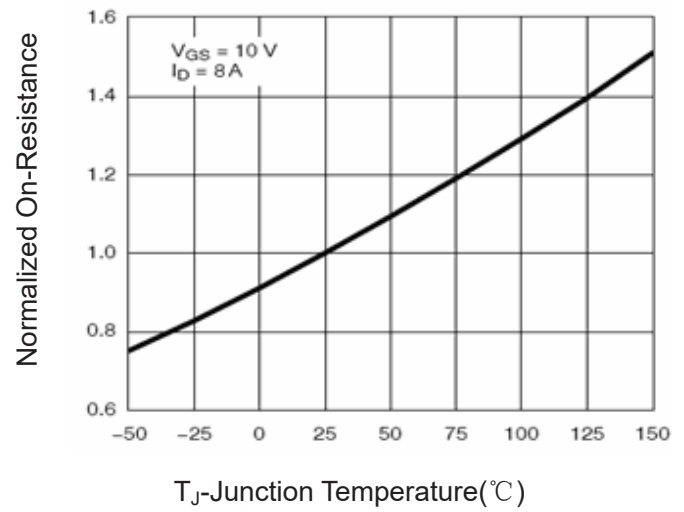
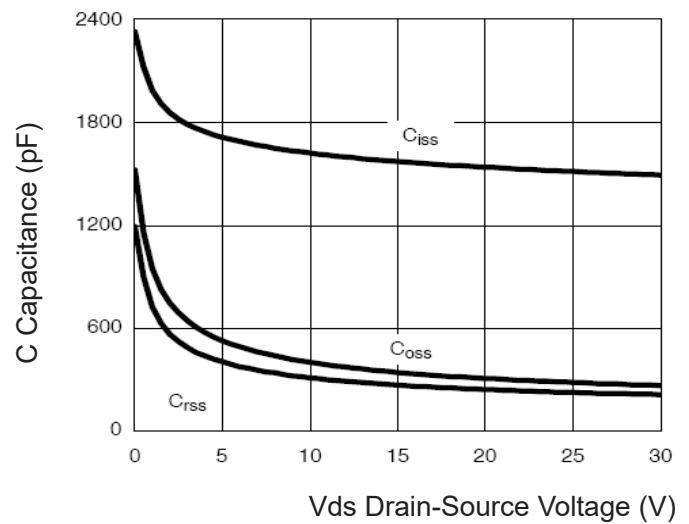
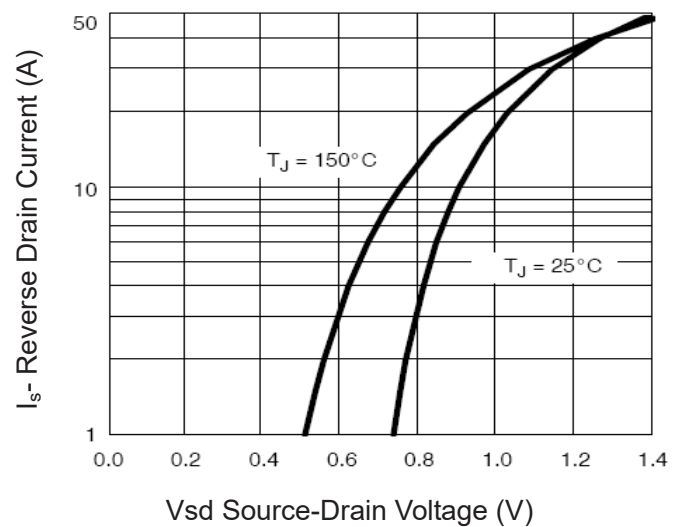
**Figure 4 Drain Current**

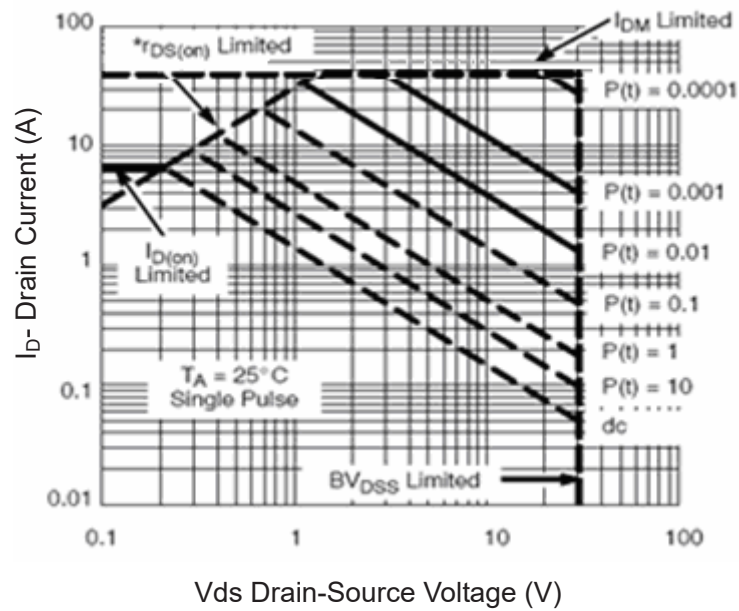


**Figure 5 Output Characteristics**

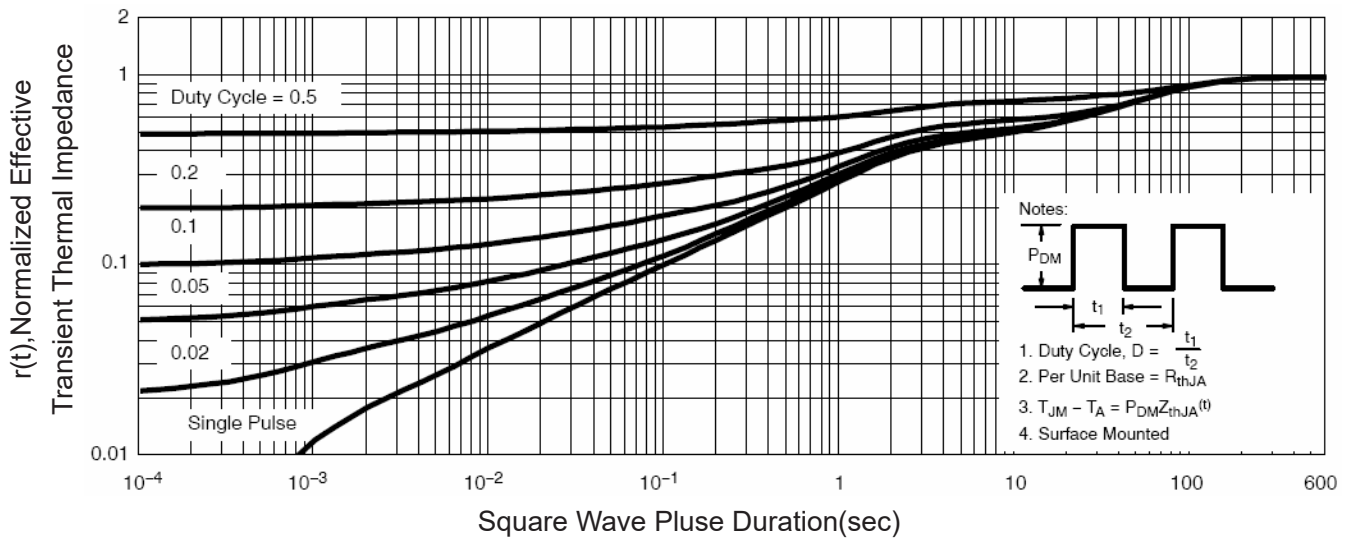


**Figure 6 Drain-Source On-Resistance**


**Figure 7 Transfer Characteristics**

**Figure 9 Rdson vs Vgs**

**Figure 11 Gate Charge**

**Figure 8 Drain-Source On-Resistance**

**Figure 10 Capacitance vs Vds**

**Figure 12 Source- Drain Diode Forward**



**Figure 13 Safe Operation Area**



**Figure 14 Normalized Maximum Transient Thermal Impedance**